



Semiconductor Device Type: H8A 006 VDFN 7x5x0.9mm NiPdAu			Termination Base Alloy: Copper Alloy (Cu)			Package Homogeneous Materials: 8.1 Electronics (e.g. pc boards, displays)			J-STD-609A Product Marking and/or Pkg. Labeling e4	
Basic Substance	CAS Number	"Contained In" Sub-Component	% Total Weight	mg/part	ppm	(mg) Total	Mold Compound	% of Total Weight	56.27	
Silica, fused	60676-86-0	Mold Compound	50.643	41.679	506,430	46.31	Silica, fused	60676-86-0	90.00	
Epoxy Resin	Trade Secret	Mold Compound	2.729	2.246	27,291		Epoxy Resin	Trade Secret	4.85	
Phenolic Resin	Trade Secret	Mold Compound	2.729	2.246	27,291		Phenolic Resin	Trade Secret	4.85	
Carbon Black	1333-86-4	Mold Compound	0.169	0.139	1,688		Carbon Black	1333-86-4	0.30	
							Total			100.00
Copper	7440-50-8	Lead Frame	39.445	32.464	394,454	33.36	Copper	7440-50-8	97.30	
Iron	7439-89-6	Lead Frame	0.932	0.767	9,324		Iron	7439-89-6	2.30	
Zinc (Metal)	7440-66-0	Lead Frame	0.101	0.083	1,014		Zinc (Metal)	7440-66-0	0.25	
Phosphorous	7723-14-0	Lead Frame	0.061	0.050	608		Phosphorous	7723-14-0	0.15	
							Total			100.00
Silver	7440-22-4	Die Attach	0.225	0.185	2,250	0.25	Silver	7440-22-4	75.00	
Methacrylic acid, isobornyl ester	7534-94-3	Die Attach	0.042	0.035	420		Methacrylic acid, isobornyl ester	7534-94-3	14.00	
1,3-Bismaleimidobenzene	3006-93-7	Die Attach	0.023	0.019	225		1,3-Bismaleimidobenzene	3006-93-7	7.50	
polymer with oxirane mono-2-propenoate	1017237-78-3	Die Attach	0.011	0.009	105		polymer with oxirane mono-2-propenoate	1017237-78-3	3.50	
							Total			100.00
Silicon	7440-21-3	Chip (Die)	1.460	1.202	14,600	1.20	Silicon	7440-21-3	100.00	
Gold	7440-57-5	Wire Bond	0.250	0.206	2,500		Total			100.00
Nickel	7440-02-0	Plating on external leads (pins)	1.112	0.915	11,118		Total			1.46
Palladium	7440-05-3	Plating on external leads (pins)	0.043	0.035	426		Total			100.00
Gold	7440-57-5	Plating on external leads (pins)	0.026	0.021	256		Total			100.00
0.0823 g Total Mass			TOTALS:	100.000	82.300	1,000,000				

This semiconductor device and its homogenous materials comply with EU Directives: 2002/95/EC (27 January 2003) & Directive 2011/65/EU (08 June 2011) and 2015/863/EU (31 March 2015) and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption (zero)

Compliance with the above EU Directives has been verified via internal design controls, supplier declarations, and/or analytical test data.

If a chemical substance is absent from the list above, the chemical substance is NOT an intentional ingredient in the semiconductor device and, to the best of Microchip Technology Incorporated's knowledge and belief as of the date of this document, there is no credible reason to believe that the unavoidable impurity concentration of the chemical substance, if any, is not below the threshold of regulatory concern for any regulatory scheme world-wide.

Molding compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You can access the UL IQTM family of databases to obtain a test report at <http://ul.com/global/eng/pages/offering/industries/chemicals/plastics/>

The protective "tubes" in which the specific product is shipped are made from polyvinyl chloride (PVC) plastic. "Window envelopes" used to hold the packing slip on the outer box and certain "reels" may be made from PVC plastic.

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Assembled package referenced above is EU REACH compliant based on the latest SVHC candidate list of ECHA which can be found at <http://echa.europa.eu/web/guest/candidate-list-table>

82.30

100.00